

## FIELD OF THE INVENTION

## BACKGROUND OF THE INVENTION

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ports 13. The key features of the process are the use of inductive coupling for plasma formation. RF power is transferred to the plasma via an RF magnetic field which in turn generates an ionizing electric field. Inductive coupling is much more efficient for plasma production than electroded systems since energy is not dissipated in driving ions into a surface. Not shown in FIG. 1 is the pumping port and throttle valve which, when used in combination with the nitrogen inlet ports 13, are used to establish the equilibrium pressure in the chamber.

Compared to earlier remote-plasma nitridation (RPN) technology, DPN improves the nitrogen uniformity and oxide leakage current considerably. However, due to its low process temperature of less than 100 °C, large amount of defects are present in the gate oxide after DPN, and the gate oxide integrity is significantly degraded. Hence, post-DPN annealing at high temperature is required to eliminate the oxide defects and improve the oxide integrity.

Such a need is known to the prior art. However, previous prior art practice has been to anneal in pure helium (at a temperature of 1,050 °C , pressure of 50 torr, with 5 slm of He flow). These conditions have become standard procedure for the prior art because they offer several advantages, such as no additional oxide growth or nitrogen incorporation during post-DPN annealing. We have, however, determined that annealing under these conditions also has several disadvantages including a deterioration of the

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electrical performance of devices (such as capacitors and transistors) when they have been subjected to pure helium annealing. The present invention discloses other post-DPN annealing methods for improving the gate oxide integrity and device electrical performance.

A routine search of the prior art was performed with the following references of interest being found:

US 6,140,187 (DeBusk et al.) reveals a remote plasma nitridation process for a gate oxide. A He/Ar plasma is used followed by an anneal in oxygen at about 800 °C . In US 5,861,329, Yeh shows a plasma process for forming a barrier layer. Gases used included nitrogen, ammonia, nitrogen oxide, and nitrogen/oxygen mixtures. US 6,225,169B1 (Chew) shows a RTN process in which the nitrided layer is formed on the sidewalls of the gate structure while in US 6,162,717, Yeh et al. use a high density plasma process in which the gate dielectric becomes sandwiched between two layers of silicon nitride.

## SUMMARY OF THE INVENTION

It has been an object of at least one embodiment of the present invention to provide

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a process for forming a field effect transistor.

Another object of at least one embodiment of the present invention has been that said field effect transistor have a gate oxide that is ultra thin, that is a barrier to boron diffusion, and that does not degrade the electrical properties of the device.

Still another object of at least one embodiment of the present invention has been that said process be easily included as part of existing manufacturing processes.

These objects have been achieved by forming a nitrogen bearing layer at the surface of the oxide by means of decoupled plasma nitridation. Following this, instead of a conventional anneal in helium or nitrogen oxide, annealing is performed in a 1:4 oxygen-nitrogen mixture (1,050 °C at about 10 torr). This results in a gate oxide that is resistant to boron contamination without suffering any loss of any of its electrical properties.

#### BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a schematic view of apparatus suitable for decoupled plasma nitridation.

FIG. 2 is a flow chart representation of the process of the present invention.

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FIG. 3 is a Weibull plot of charge vs. breakdown ratio for three oxide layers annealed in different gases.

## DESCRIPTION OF THE PREFERRED EMBODIMENTS

We will disclose the present invention by describing a process for the manufacture of a field effect transistor. It will, however, be understood that the process is more general than this and could be applied to other areas of semiconductor technology as well.

The process begins with the provision of a silicon wafer and forming thereon a layer of silicon oxide (typically between about 8 and 30 Angstroms thick). Then, by means of decoupled plasma nitridation using equipment similar to that illustrated in FIG. 1, a nitrogen bearing layer is formed at its upper surface, extending downwards therefrom a distance of between about 2 and 10 Angstroms. This nitrogen bearing layer could be silicon nitride or silicon oxynitride but, regardless of its exact chemical composition, it will contain at least 3 atomic percent nitrogen..

Now follows a key feature of the invention wherein this nitrogen bearing layer is annealed in a mixture of nitrogen and oxygen (having between about 10 and 30 volume percent oxygen with 20% being preferred), at a temperature between about 1,000 and

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1,100 °C and a pressure between about 5 and 16 torr, for between about 60 and 150 minutes. As a result of this special anneal, under the conditions specified, the gate oxide layer, including the nitrogen rich layer, becomes substantially free of structural defects. An indication of this improvement can be seen by noting that, prior to the annealing step, the nitrogen bearing layer typically would have a significant concentration of structural defects which, after annealing, will be reduced substantially.

Formation of the field effect transistor is then completed using standard processes including depositing a layer of polysilicon on the layer of silicon oxide and then patterning and etching the former so as to form a gate pedestal (typically having a width between about 0.05 and 0.25 microns) on a layer of gate oxide. Once this has been completed, the gate pedestal is used as a mask during the formation of the source and drain regions (of a conductivity type that is the opposite of that of the silicon wafer) that are self-aligned so that they immediately abut the gate oxide. The above described process has been illustrated and summarized in the flow chart that is shown in FIG. 2.

Using the process described above (in particular the conditions that are specified for the post nitridation anneal), a field effect transistor is formed whose electrical performance is similar to that of a device formed under identical conditions, the only difference being the absence of a nitrogen bearing layer that was formed by decoupled plasma nitridation. Thus the process of the present invention continues to provide a gate

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oxide layer that suppresses boron penetration and reduces the oxide leakage but without the deterioration in electrical performance associated with prior art processes.

Confirmation of the effectiveness of the process of the present invention is shown in FIG. 3 where we display Weibull plots of charge-to-breakdown ratio (in units of coulombs per sq. cm) for annealing a 20 Å thick oxide layer in three different gases. A Weibull plot is  $-\ln(1-F)$ , where F is the cumulative failure probability, ranging from 0 to 1. Curve 31 is for a helium anneal, curve 32 is for a nitrogen oxide anneal, and curve 33 is for nitrogen/oxygen anneal (present invention). These results confirm that annealing in  $N_2/O_2$  at about 1,050 °C, as taught by the present invention, results in a gate oxide having the highest dielectric endurance.

What is claimed is: